

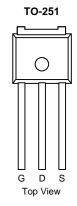
# AP9561AGJ-HF-VB Datasheet P-Channel 40 V (D-S) MOSFET

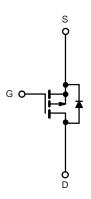
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>			
- 40	$0.010 \text{ at V}_{GS} = -10 \text{ V}$	± 55			
- 40	0.014 at V <sub>GS</sub> = - 4.5 V	± 54			

### **FEATURES**

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

Parameter	Symbol	Limit ± 40	Unit V		
Gate-Source Voltage	V <sub>GS</sub>				
Continuous Drain Current (T. 175 °C)	T <sub>C</sub> = 25 °C	,	- 55 <sup>a</sup>		
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	- 52		
Pulsed Drain Current	I <sub>DM</sub>	- 220	Α		
Avalanche Current	I <sub>AR</sub>	- 60			
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	180	mJ	
Dower Discipation	T <sub>C</sub> = 25 °C	D	45	W	
Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.75	7 **	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) <sup>c</sup>	В	40			
Junction-to-Ambient	Free Air (TO-220AB)	R <sub>thJA</sub>	62.5	°C/W		
Junction-to-Case	•	R <sub>thJC</sub>	0.8	1		

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage		$V_{GS} = 0 \text{ V, } I_{D} = -250  \mu\text{A}$	- 40				
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μA	
		V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.010			
Drain-Source On-State Resistance <sup>a</sup>	ь	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C		0.016			
Diani-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C		0.023		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.014			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 75 A	20			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		620			
Reversen Transfer Capacitance	C <sub>rss</sub>			315			
Total Gate Charge <sup>c</sup>	$Q_g$			160			
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 75 A		32		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			30		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			25	40		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240		
Fall Time <sup>c</sup>	t <sub>f</sub>			210	340		
Source-Drain Diode Ratings and Cha	racteristics <sup>b</sup>	(T <sub>C</sub> = 25 °C)					
Continuous Current	I <sub>S</sub>			- 220		۸	
Pulsed Current	I <sub>SM</sub>				- 240	Α	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = -75 A, V <sub>GS</sub> = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			55	100	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.07	0.25	иC	

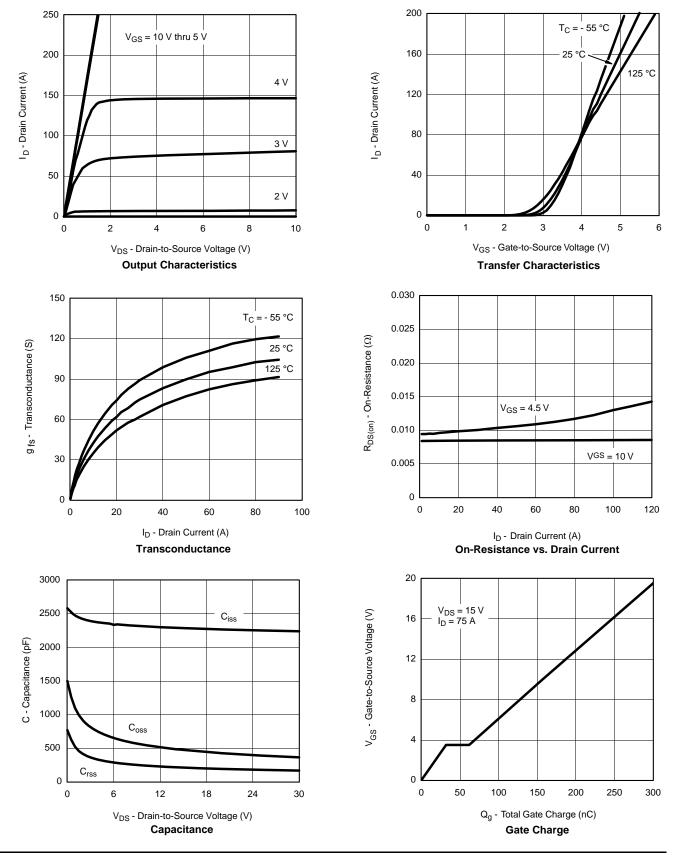
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

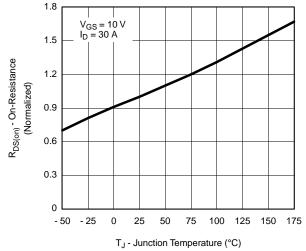


### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

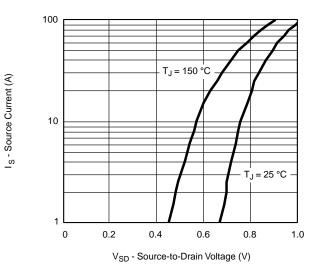




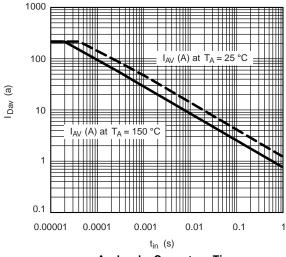
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



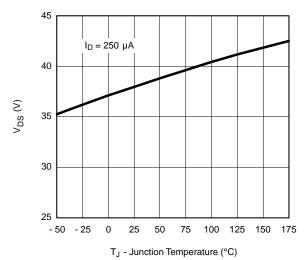
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



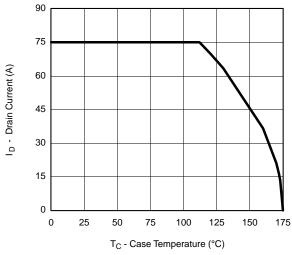
Avalanche Current vs. Time

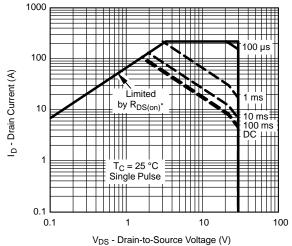


**Drain Source Breakdown** vs. Junction Temperature



#### THERMAL RATINGS

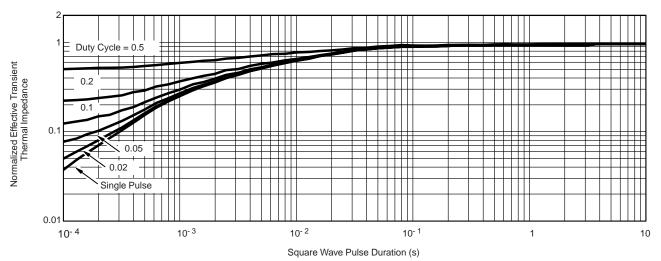




Maximum Avalanche and Drain Current vs. Case Temperature

\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

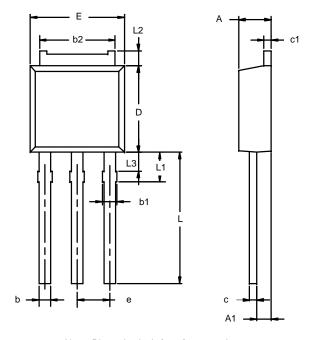
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



## TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INC	HES		
Dim	Min	Max	Min	Max		
Α	2.21	2.38	0.087	0.094		
A1	0.89	1.14	0.035	0.045		
b	0.71	0.89	0.028	0.035		
b1	0.76	1.14	0.030	0.045		
b2	5.23	5.43	0.206	0.214		
С	0.46	0.58	0.018	0.023		
с1	0.46	0.58	0.018	0.023		
D	5.97	6.22	0.235	0.245		
E	6.48	6.73	0.255	0.265		
е	2.28	BSC	0.090 BSC			
L	8.89	9.53	0.350	0.375		
L1	1.91	2.28	0.075	0.090		
L2	0.89	1.27	0.035	0.050		
L3	1.15	1.52	0.045	0.060		
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346						



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